



# PMN55ENEA

60 V, N-channel Trench MOSFET

1 March 2021

Product data sheet

## 1. General description

N-channel enhancement mode Field-Effect Transistor (FET) in a small SOT457 (SC-74) Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

## 2. Features and benefits

- Logic-level compatible
- Extended temperature range  $T_j = 175\text{ }^{\circ}\text{C}$
- Trench MOSFET technology
- ElectroStatic Discharge (ESD) protection  $> 2\text{ kV HBM (class H2)}$
- AEC-Q101 qualified

## 3. Applications

- Relay driver
- High-speed line driver
- Low-side load switch
- Switching circuits

## 4. Quick reference data

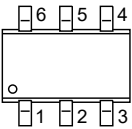
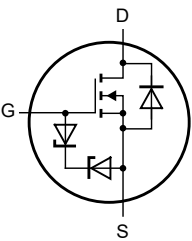
Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$V_{DS}$	drain-source voltage	$T_j = 25\text{ }^{\circ}\text{C}$		-	-	60	V
$V_{GS}$	gate-source voltage			-20	-	20	V
$I_D$	drain current	$V_{GS} = 10\text{ V}; T_{amb} = 25\text{ }^{\circ}\text{C}$	[1]	-	-	3.6	A
<b>Static characteristics</b>							
$R_{DSon}$	drain-source on-state resistance	$V_{GS} = 10\text{ V}; I_D = 3.6\text{ A}; T_j = 25\text{ }^{\circ}\text{C}$		-	46	60	m $\Omega$

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and mounting pad for drain  $6\text{ cm}^2$ .

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	D	drain	 SC-74; TSOP6 (SOT457)	 017aaa255
2	D	drain		
3	G	gate		
4	S	source		
5	D	drain		
6	D	drain		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMN55ENEA	SC-74; TSOP6	plastic, surface-mounted package (SC-74; TSOP6); 6 leads	SOT457

7. Marking

Table 4. Marking codes

Type number	Marking code
PMN55ENEA	J4

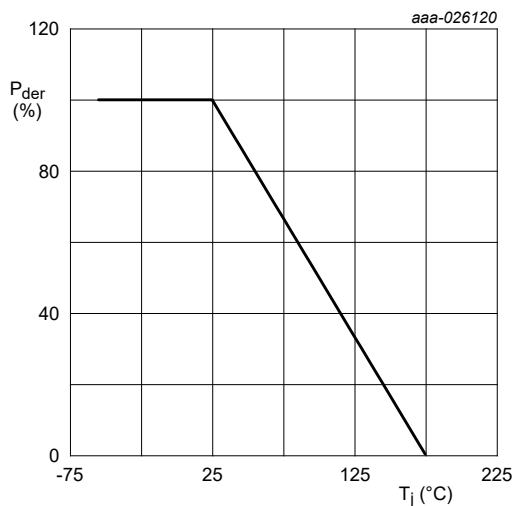
## 8. Limiting values

**Table 5. Limiting values**

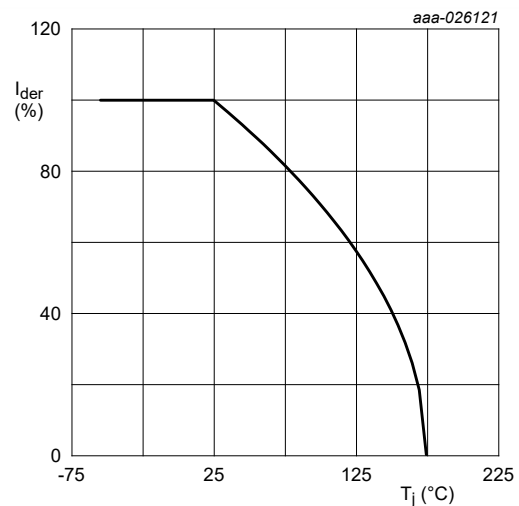
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
$V_{DS}$	drain-source voltage	$T_J = 25\text{ }^{\circ}\text{C}$		-	60	V
$V_{GS}$	gate-source voltage			-20	20	V
$I_D$	drain current	$V_{GS} = 10\text{ V}; T_{amb} = 25\text{ }^{\circ}\text{C}$	[1]	-	3.6	A
		$V_{GS} = 10\text{ V}; T_{amb} = 100\text{ }^{\circ}\text{C}$	[1]	-	2.5	A
$I_{DM}$	peak drain current	$T_{amb} = 25\text{ }^{\circ}\text{C}$ ; single pulse; $t_p \leq 10\text{ }\mu\text{s}$		-	14	A
$P_{tot}$	total power dissipation	$T_{amb} = 25\text{ }^{\circ}\text{C}$	[2]	-	667	mW
			[1]	-	1.7	W
		$T_{sp} = 25\text{ }^{\circ}\text{C}$		-	7.5	W
$T_J$	junction temperature			-55	175	$^{\circ}\text{C}$
$T_{amb}$	ambient temperature			-55	175	$^{\circ}\text{C}$
$T_{stg}$	storage temperature			-65	175	$^{\circ}\text{C}$
<b>Source Drain Diode</b>						
$I_S$	source current	$T_{amb} = 25\text{ }^{\circ}\text{C}$	[1]	-	1.7	A
<b>ESD maximum rating</b>						
$V_{ESD}$	electrostatic discharge voltage	HBM	[3]	-	2000	V
<b>Avalanche ruggedness</b>						
$E_{DS(AL)S}$	non-repetitive drain-source avalanche energy	$T_{J(\text{init})} = 25\text{ }^{\circ}\text{C}$ ; $I_D = 0.5\text{ A}$ ; DUT in avalanche (unclamped)		-	15.4	mJ

- [1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and mounting pad for drain 6 cm<sup>2</sup>.  
 [2] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.  
 [3] Measured between all pins.



**Fig. 1. Normalized total power dissipation as a function of junction temperature**



**Fig. 2. Normalized continuous drain current as a function of junction temperature**

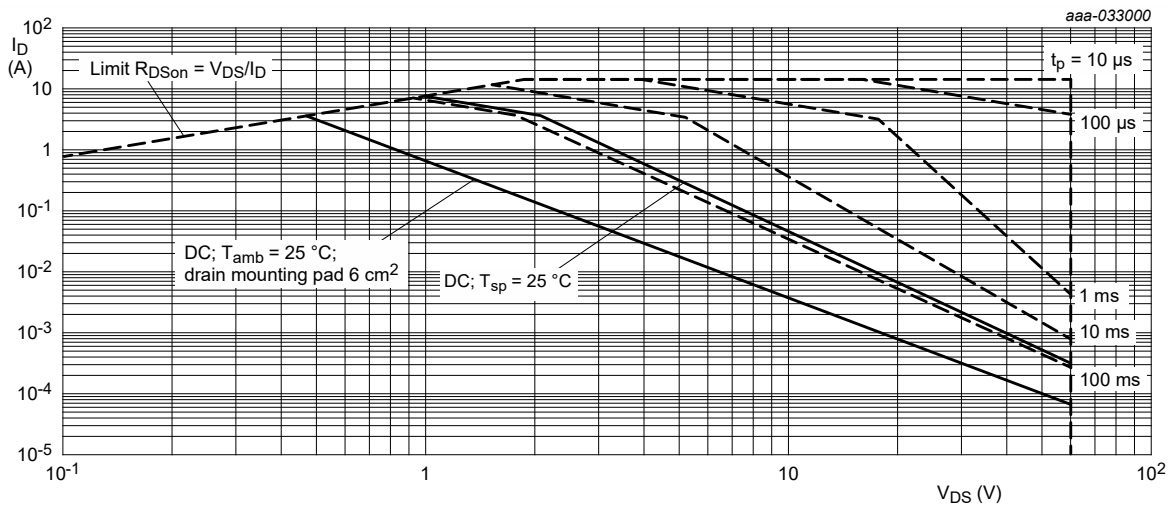


Fig. 3. Safe operating area; junction to ambient; continuous and peak drain currents as a function of drain-source voltage

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	195	225	K/W
			[2]	-	78	90	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point			-	15	20	K/W

- [1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.  
[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and mounting pad for drain 6 cm<sup>2</sup>.

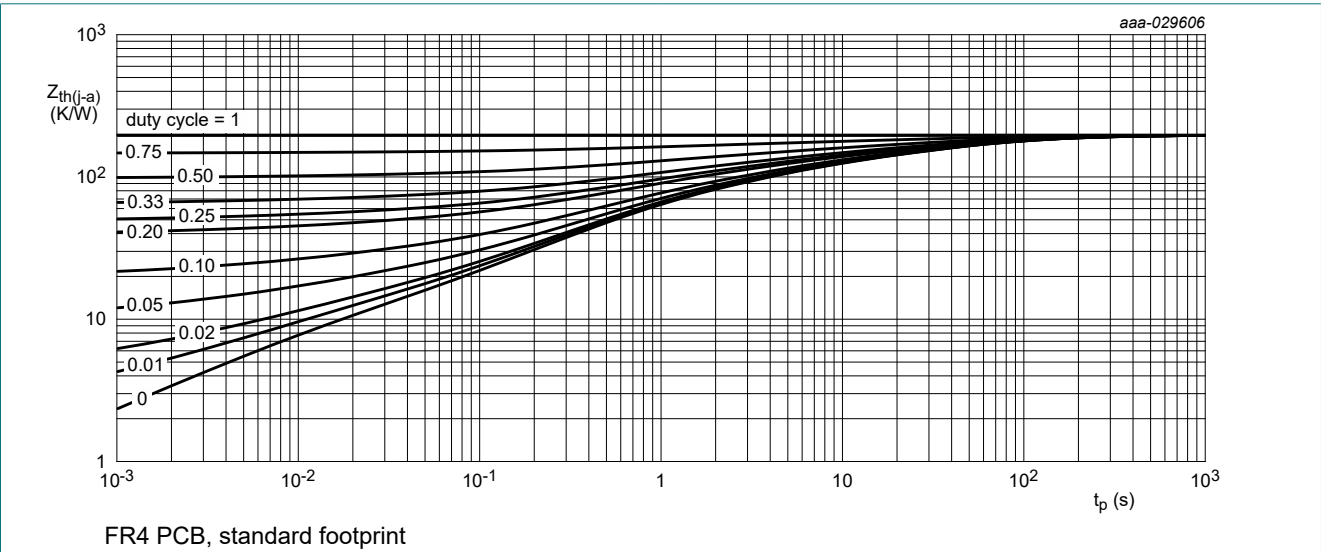


Fig. 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

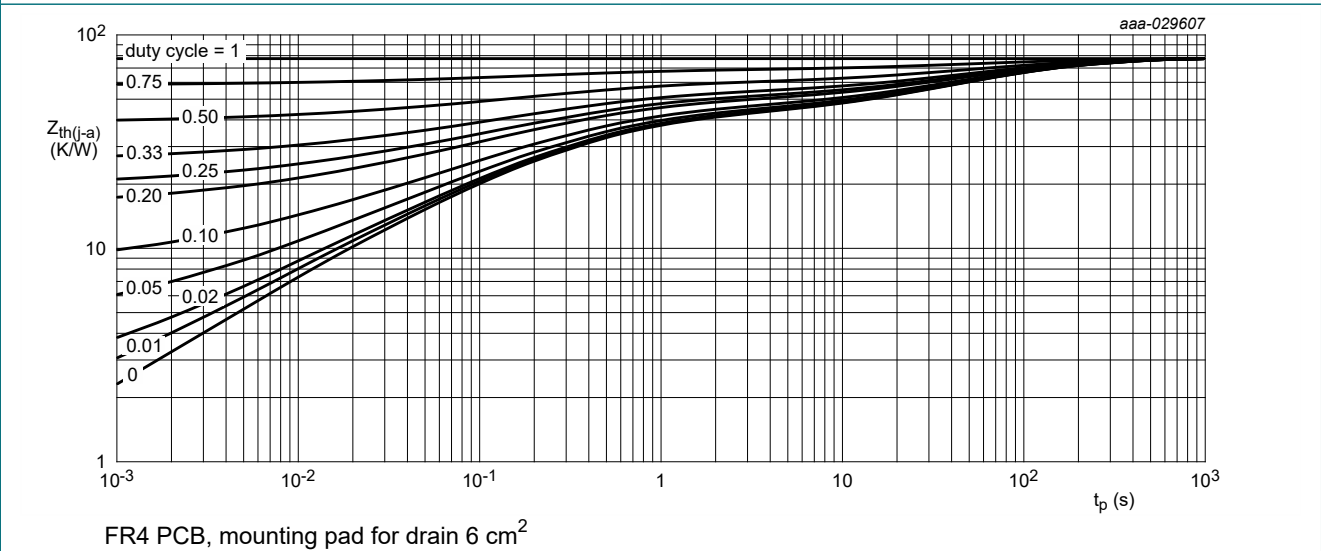


Fig. 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

## 10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
V <sub>(BR)DSS</sub>	drain-source breakdown voltage	I <sub>D</sub> = 250 μA; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C		60	-	-	V
V <sub>GSth</sub>	gate-source threshold voltage	I <sub>D</sub> = 250 μA; V <sub>DS</sub> = V <sub>GS</sub> ; T <sub>j</sub> = 25 °C		1.3	1.7	2.7	V
I <sub>DSS</sub>	drain leakage current	V <sub>DS</sub> = 60 V; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C		-	-	1	μA
I <sub>GSS</sub>	gate leakage current	V <sub>GS</sub> = 20 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C		-	-	10	μA
		V <sub>GS</sub> = -20 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C		-	-	-10	μA
		V <sub>GS</sub> = 10 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C		-	-	1	μA
		V <sub>GS</sub> = -10 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C		-	-	-1	μA
R <sub>DSon</sub>	drain-source on-state resistance	V <sub>GS</sub> = 10 V; I <sub>D</sub> = 3.6 A; T <sub>j</sub> = 25 °C		-	46	60	mΩ
		V <sub>GS</sub> = 10 V; I <sub>D</sub> = 3.6 A; T <sub>j</sub> = 175 °C		-	100	130	mΩ
		V <sub>GS</sub> = 4.5 V; I <sub>D</sub> = 3.3 A; T <sub>j</sub> = 25 °C		-	52	70	mΩ
g <sub>fs</sub>	forward transconductance	V <sub>DS</sub> = 10 V; I <sub>D</sub> = 3.6 A; T <sub>j</sub> = 25 °C		-	18.2	-	S
R <sub>G</sub>	gate resistance	f = 1 MHz		-	2	-	Ω
Dynamic characteristics							
Q <sub>G(tot)</sub>	total gate charge	V <sub>DS</sub> = 30 V; I <sub>D</sub> = 3.1 A; V <sub>GS</sub> = 10 V; T <sub>j</sub> = 25 °C		-	8.8	13.2	nC
Q <sub>GS</sub>	gate-source charge			-	1.1	-	nC
Q <sub>GD</sub>	gate-drain charge			-	1.8	-	nC
C <sub>iss</sub>	input capacitance	V <sub>DS</sub> = 30 V; f = 1 MHz; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C		-	450	-	pF
C <sub>oss</sub>	output capacitance			-	49	-	pF
C <sub>rss</sub>	reverse transfer capacitance			-	30	-	pF
t <sub>d(on)</sub>	turn-on delay time	V <sub>DS</sub> = 30 V; I <sub>D</sub> = 3.1 A; V <sub>GS</sub> = 10 V; R <sub>G(ext)</sub> = 6 Ω; T <sub>j</sub> = 25 °C		-	5	-	ns
t <sub>r</sub>	rise time			-	7	-	ns
t <sub>d(off)</sub>	turn-off delay time			-	13	-	ns
t <sub>f</sub>	fall time			-	4	-	ns
Source-drain diode							
V <sub>SD</sub>	source-drain voltage	I <sub>S</sub> = 1.7 A; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C		-	0.8	1.2	V
t <sub>rr</sub>	reverse recovery time	I <sub>S</sub> = 1.4 A; dI <sub>S</sub> /dt = -100 A/μs; V <sub>GS</sub> = 0 V; V <sub>DS</sub> = 30 V; T <sub>j</sub> = 25 °C		-	13	-	ns
Q <sub>r</sub>	recovered charge			-	6	-	nC

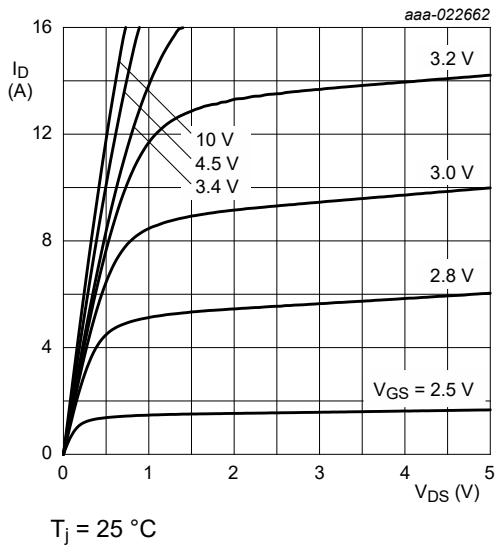


Fig. 6. Output characteristics: drain current as a function of drain-source voltage; typical values

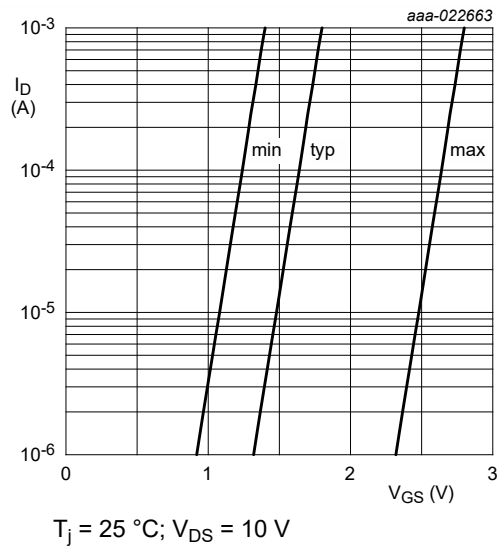


Fig. 7. Sub-threshold drain current as a function of gate-source voltage

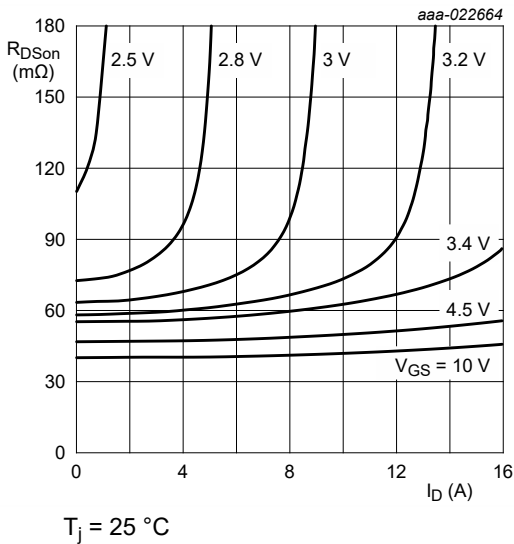


Fig. 8. Drain-source on-state resistance as a function of drain current; typical values

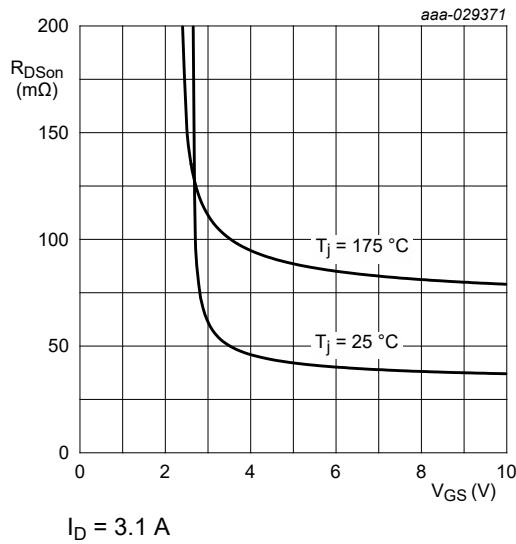


Fig. 9. Drain-source on-state resistance as a function of gate-source voltage; typical values

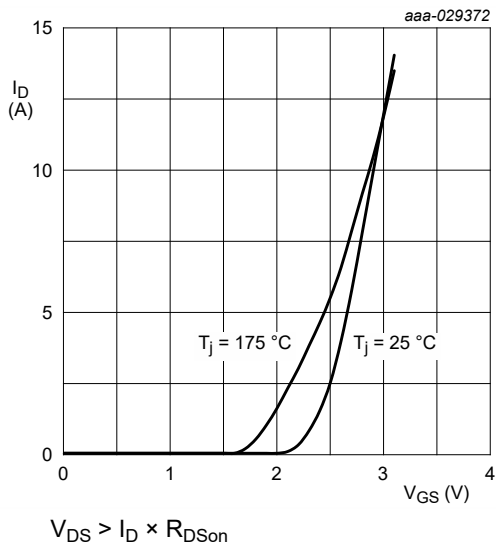


Fig. 10. Transfer characteristics: drain current as a function of gate-source voltage; typical values

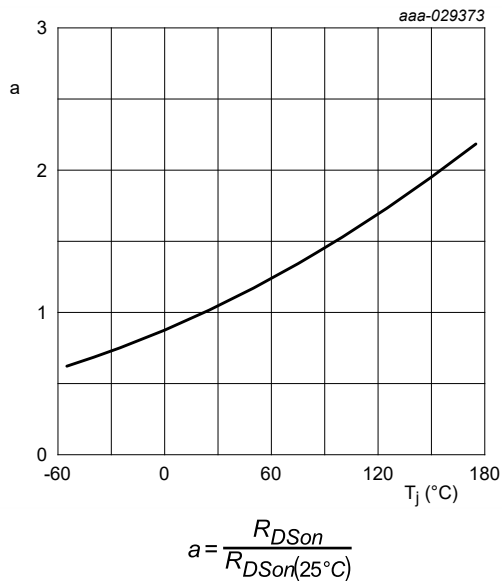


Fig. 11. Normalized drain-source on-state resistance as a function of junction temperature; typical values

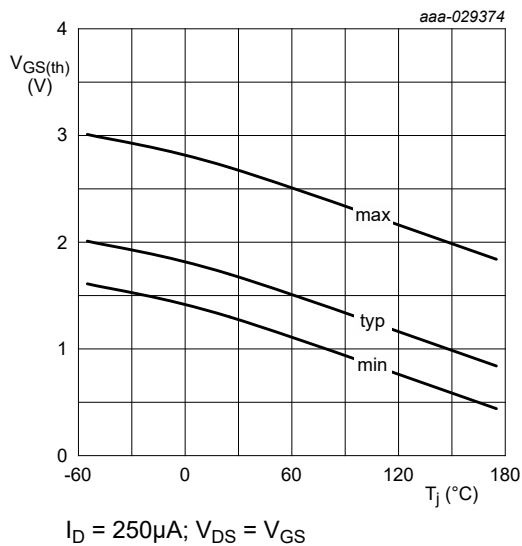


Fig. 12. Gate-source threshold voltage as a function of junction temperature

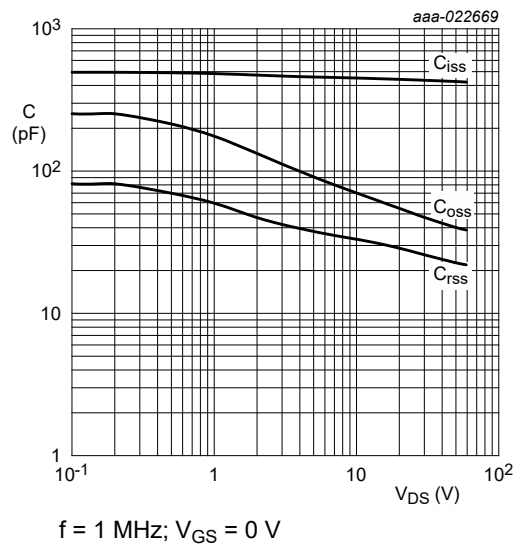


Fig. 13. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values



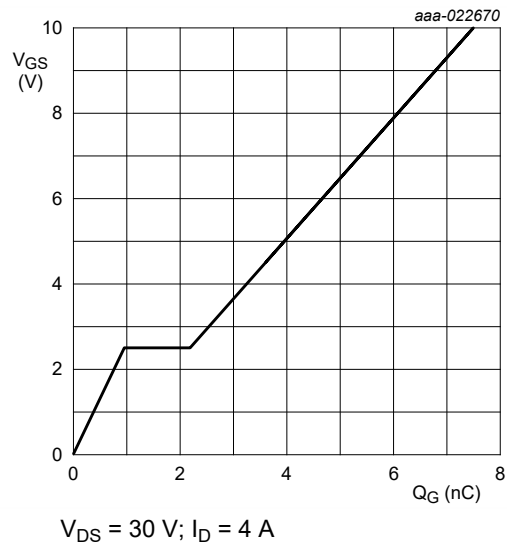


Fig. 14. Gate-source voltage as a function of gate charge; typical values

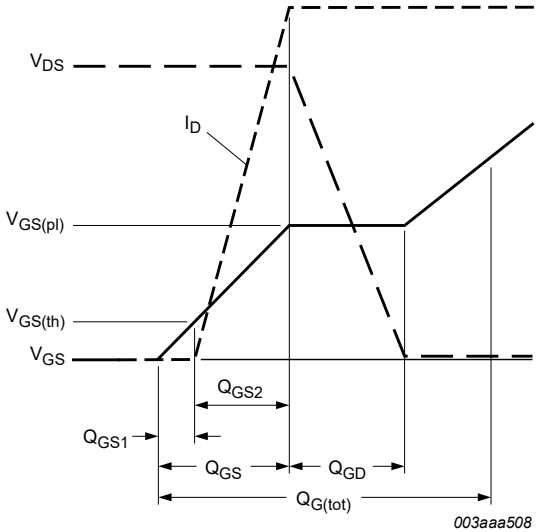


Fig. 15. Gate charge waveform definitions

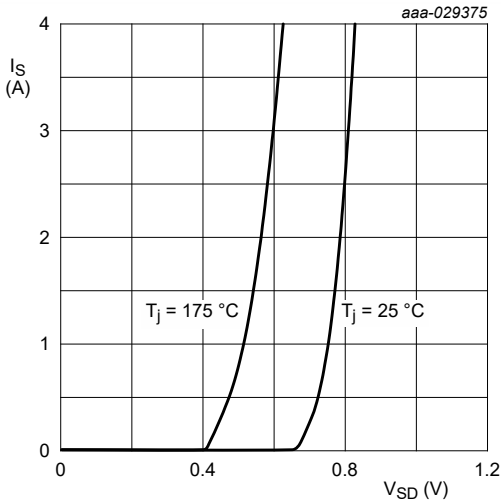


Fig. 16. Source current as a function of source-drain voltage; typical values

## 11. Test information

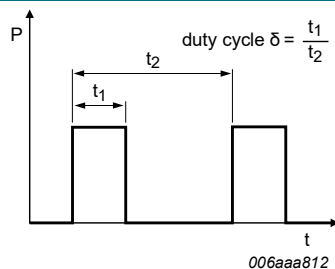


Fig. 17. Duty cycle definition

### Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

12. Package outline

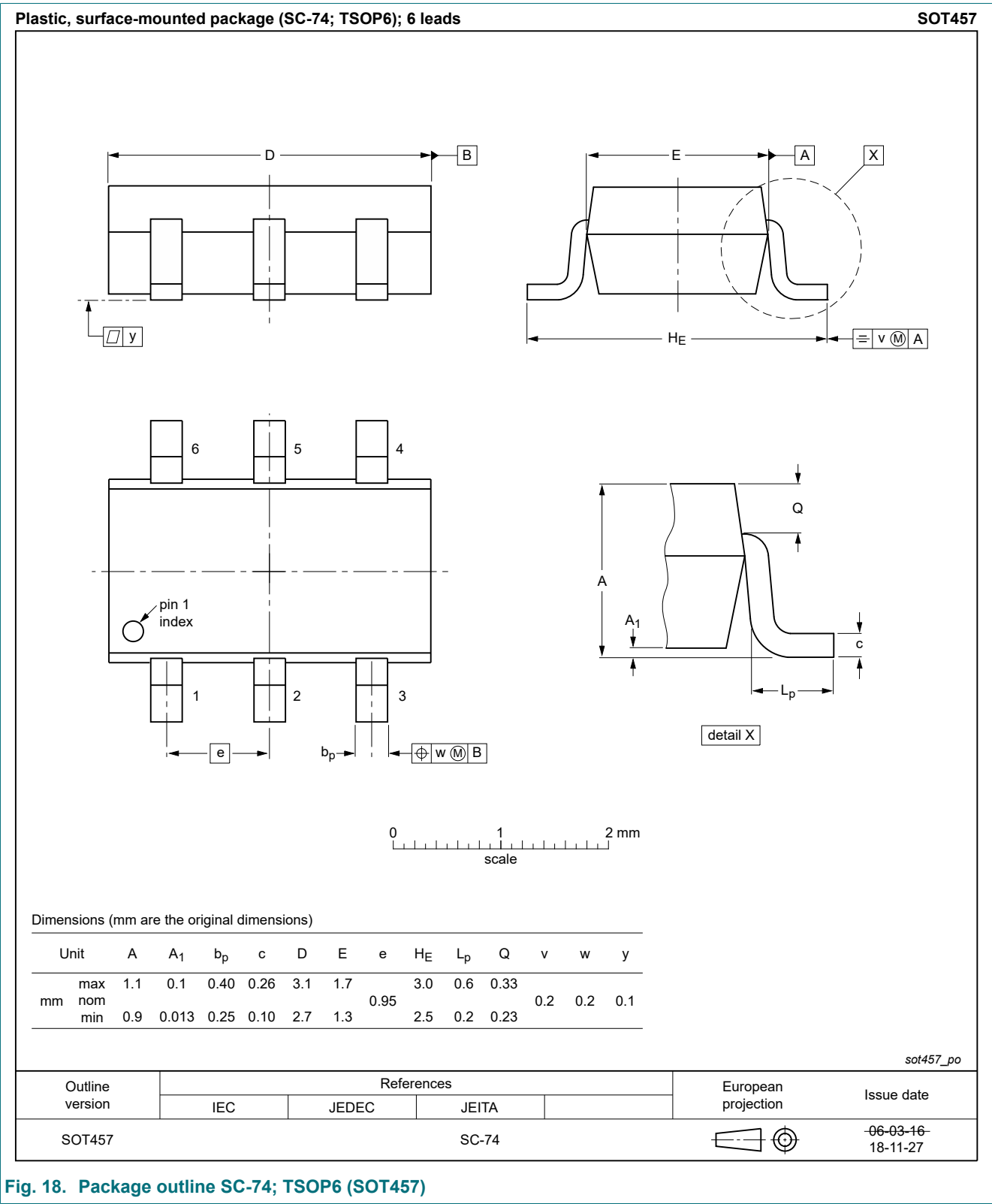
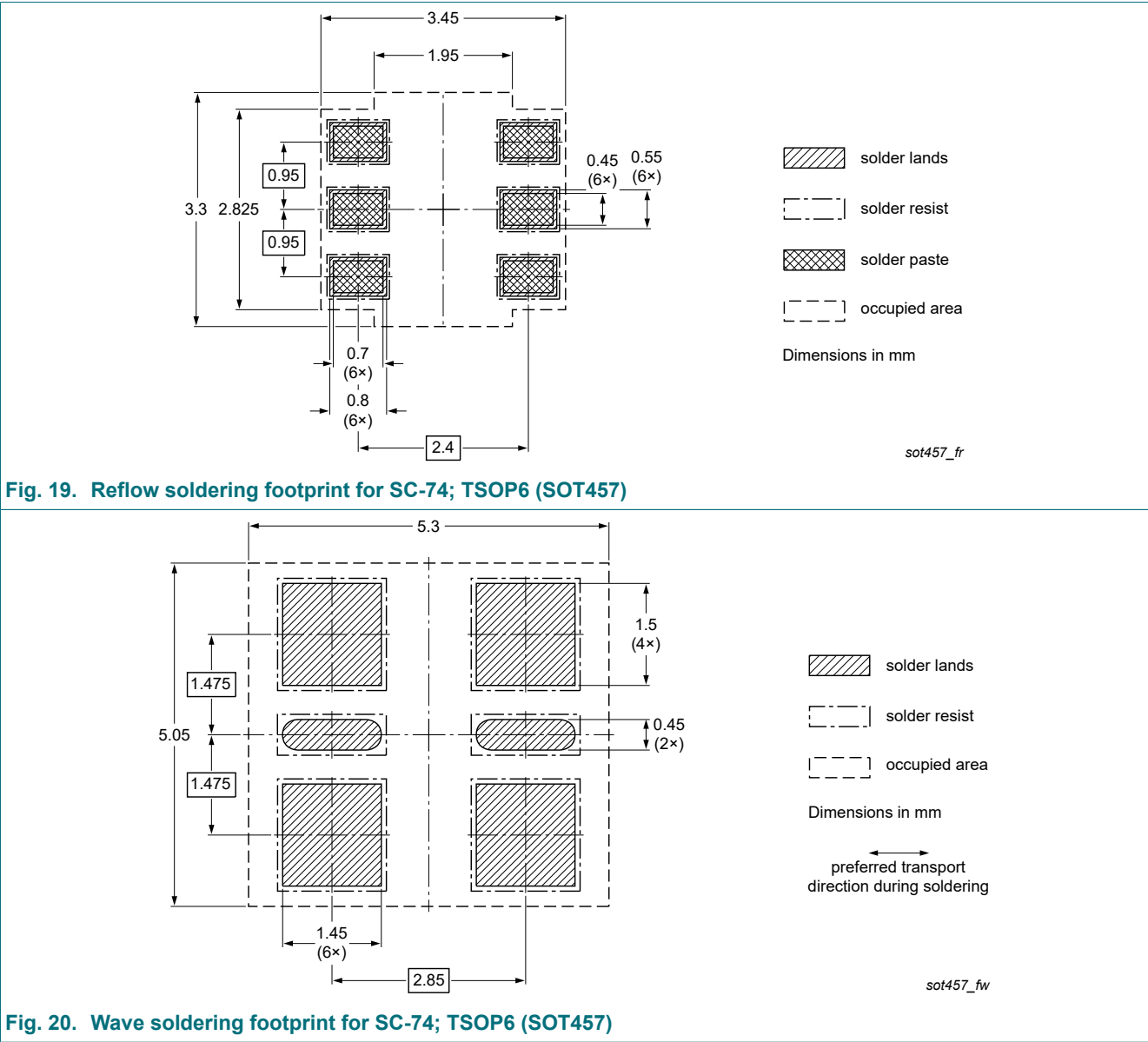


Fig. 18. Package outline SC-74; TSOP6 (SOT457)

13. Soldering



## 14. Revision history

**Table 8. Revision history**

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMN55ENEA v.2	20210301	Product data sheet	-	PMN55ENEA v.1
Modifications:	<ul style="list-style-type: none"><li>Chapter "Limiting values": Figure 3 updated</li><li>Chapter "Thermal characteristics": Figure 4 and Figure 5 updated</li></ul>			
PMN55ENEA v.1	20190426	Product data sheet	-	-

## 15. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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Date of release: 1 March 2021

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